In the Specification:

Please amend paragraph [0001] on page 1 as follows:

--This application claims the benefit under 35 U.S.C. § 120 to PCT application

PCT/DE02/03830, filed on October 11, 2002, entitled "Probe Needle for Testing Semiconductor

Chips and Method for Producing Said Probe Needle" and was not published in English on May

1, 2003 as International Publication No. WO 03/035541 A2, and which is based on German

Application No. 101 50 291.5, filed October 15, 2001, both of which application is applications

are hereby incorporated herein by reference.